

METHOD OF FORMING HSQFN TYPE PACKAGE

Abstract of the Disclosure

5 A method of forming a HSQFN (High Stand-off Quad  
Flat Non-leaded) package comprises providing a  
leadframe with bonding pads and die pads for receiving  
a die. Then, the die is attached on the die pad and  
bonding wires are connected between the bonding pads  
and the die for electrical connection. Molding  
10 process is used to encompass the die by compound from  
a first surface of the leadframe. Then, backside  
etching is used to etch the leadframe from a second  
surface of the leadframe to expose a lower surface of  
the compound, thereby separating the bonding pads and  
15 the die pads. A singulation is applied to separate each  
individual package by cutting the leadframe and the  
compound.

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